Medium Voltage Low Dissipation Factor Specifications and Test Methods

| lo. Item | | Specifications | Test Method | | |
|---|-------------|--|--|--|---|
| 1 Operating Temperature Range | | -55 to +125℃ | - | | |
| 2 Appearance | | No defects or abnormalities | Visual inspection | | |
| 3 Dimensions | | Within the specified dimension | Using calipers and micrometers | | |
| 4 Dielectric Strength | | No defects or abnormalities | No failure should be observed when voltage in the Table is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA. Rated Voltage Test Voltage DC250V 200% of the rated voltage DC630V 150% of the rated voltage DC1kV, DC2kV, DC3.15kV 130% of the rated voltage | | 5 sec., provided the nA. Voltage e rated voltage e rated voltage |
| 5 Insulation Resistance (I.R.) | | More than 10,000M Ω | The insulation resistance should be measured with DC500±50V (DC250±25V in case of rated voltage: DC250V) and within 60±5 sec. of charging. | | |
| 6 Capacitance | | Within the specified tolerance | The capacitance/Q should be measured at the frequency and | | |
| 7 Q | | 1,000 min. | voltage shown as follows. Capacitance C<1,000pF C≥1,000pF | Frequency 1±0.2MHz 1±0.2kHz | Voltage AC0.5 to 5V(r.m.s.) AC1±0.2V(r.m.s.) |
| Capacitance 8 Temperature Characteristics | | Temp. Coefficient C0G char.: 0±30ppm/°C (Temp. Range: +25 to +125°C) 0+30, -72ppm/°C (Temp. Range: -55 to +25°C) U2J char.: -750±120ppm/°C (Temp. Range: +25 to +125°C) -750+120, -347ppm/°C (Temp. Range: -55 to +25°C) | The capacitance measure specified in the Table. Step 1 2 3 4 5 | p Temperature (°C) 25±2 Min. Operating Temp.±3 | |
| 9 Adhesive Strength of Termination | | No removal of the terminations or other defect should occur. | Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1. Then apply 10N force in the direction of the arrow. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. | | |
| | Appearance | No defects or abnormalities | Solder the capacitor to the test jig (glass epoxy board). | | |
| Vibration Resistance | Capacitance | Within the specified tolerance | The capacitor should be so | • | • |
| | Q | 1,000 min. | having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.). | | |
| | 9 | | | Q 1,000 min. | Q 1,000 min. |

Continued on the following page.



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\(\) Continued from the preceding page.

| No. | o. Item | | Specifications | Test Method | | |
|--------|------------------------|------------------------|---|--|--|--|
| 11 | 1 Deflection | | No marking defects | Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2. Then apply a force in the direction shown in Fig. 3. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 20 50 Pressurizing speed: 1.0mm/s Pressurize Pressurize Flexure=1 Capacitance meter 45 (in mm) Fig. 3 | | |
| 12 | Solderabi Terminati | | 75% of the terminations are to be soldered evenly and continuously. | rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 sec. Immersing speed: 25±2.5mm/s Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder | | |
| | | Appearance | No marking defects | Preheat the capacitor at 120 to 150℃* for 1 min. Immerse the capacitor in solder solution at 260±5℃ for 10±1 sec. | | |
| | Resistance | Capacitance Change | Within ±2.5% | Let sit at room condition* for 24±2 hrs., then measure. Immersing speed: 25±2.5mm/s *Preheating for more than 3.2×2.5mm | | |
| 13 | to Soldering Heat | Q I.R. | 1,000 min. More than 10,000M Ω | | | |
| | | | | Step Temperature Time | | |
| | | Dielectric Strength | In accordance with item No.4 | 1 100 to 120°C 1 min. 2 170 to 200°C 1 min. | | |
| | | Appearance | No marking defects Fix the capacitor to the supporting jig (glass epoxy box | | | |
| | | Capacitance Change | Within ±2.5% | in Fig. 4. Perform the 5 cycles according to the 4 heat treatments listed in the following table. | | |
| | | Q I.R. | 500 min. More than 10,000MΩ | Let sit for 24±2 hrs. at room condition,* then measure. Step Temperature (°C) Time (min.) | | |
| 14 | Temperature Cycle | Dielectric Strength | In accordance with item No.4 | 1 Min. Operating Temp.±3 30±3 2 Room Temp. 2 to 3 3 Max. Operating Temp.±2 30±3 4 Room Temp. 2 to 3 4 Room Temp. 2 to 3 Solder resist Glass Epoxy Board Fig. 4 | | |
| | | Appearance | No marking defects | | | |
| | Humidity | Capacitance Change | Within ±5.0% | Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500 ^{±2} d hrs. Remove and let sit for 24±2 hrs. at room condition,* then measure. | | |
| 15 | (Steady State) | Q | 350 min. | | | |
| States | , , , | I.R. | More than 1,000MΩ | | | |
| | | Dielectric Strength | In accordance with item No.4 | | | |
| | | Appearance | No marking defects | Apply voltage as in Table for 1,000 ^{±48} ohrs. at maximum | | |
| | | Capacitance Change | Within ±3.0% | operating temperature ±3°C. Remove and let sit for 24±2 hrs. at room condition,* then measure. | | |
| | Lifo | Q | 350 min. | Rated Voltage Applied Voltage | | |
| 16 | Life | I.R. | More than 1,000M Ω | DC250V 150% of the rated voltage | | |

^{* &}quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

